

4

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D

D

C

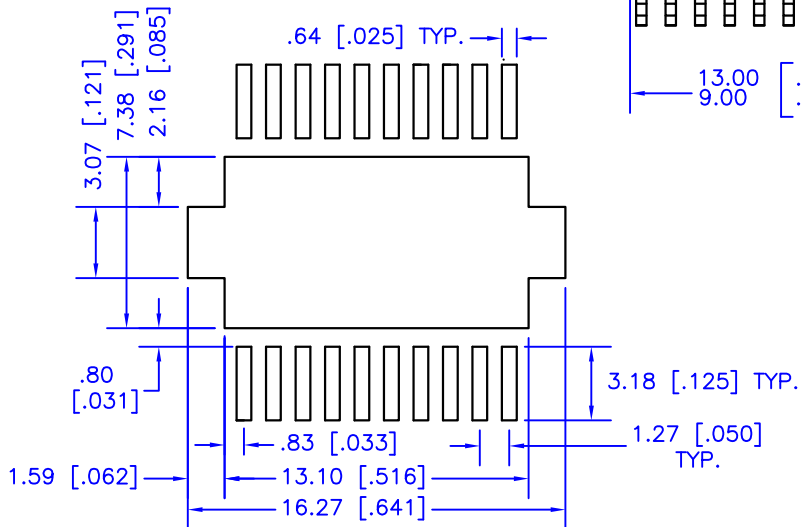
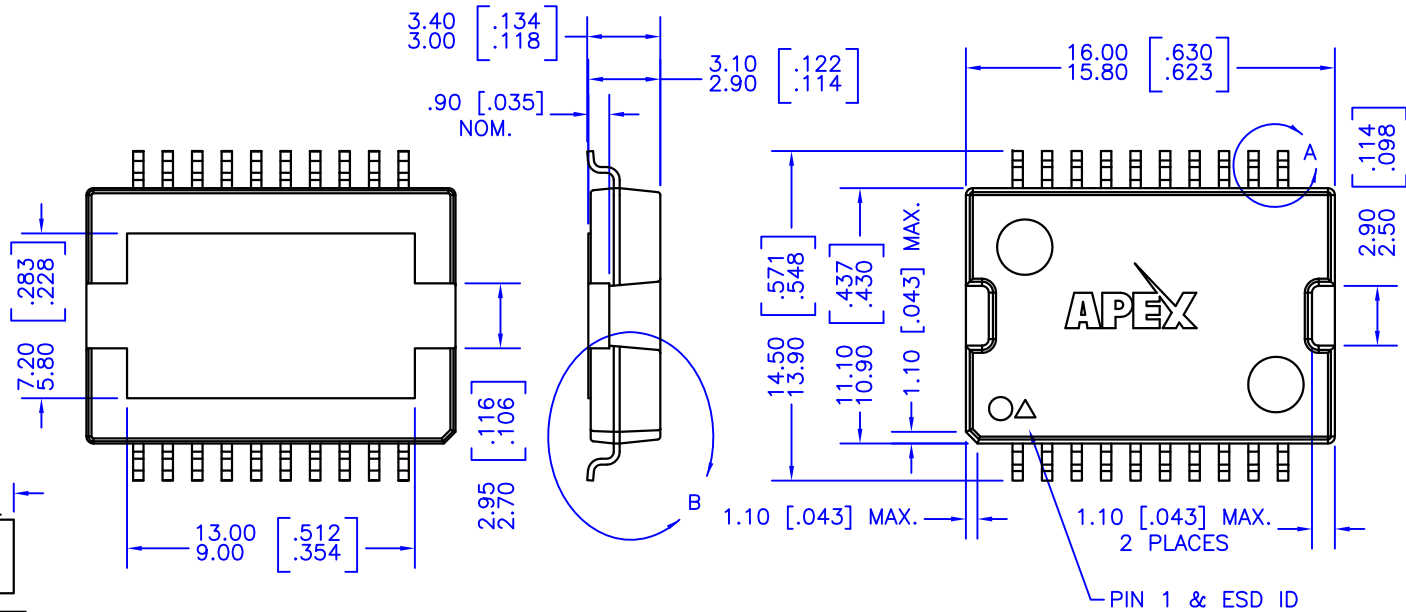
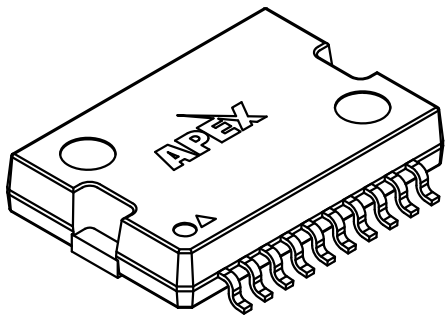
C

B

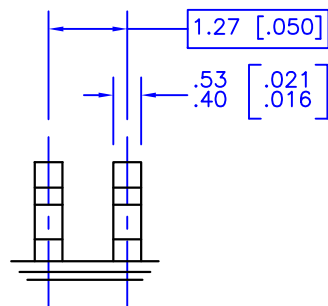
B

A

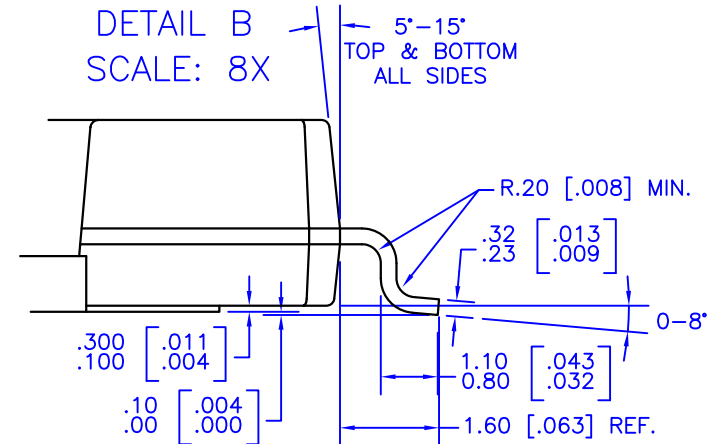
A



Surface Mount Layout



DETAIL A
SCALE: 8X



DETAIL B
SCALE: 8X
5°-15°
TOP & BOTTOM
ALL SIDES

NOTES:

1. Dimensions are millimeters & [inches].
2. Bracketed alternate units are for reference only.
3. Dimple on lid & ESD triangle denote pin 1.
4. Heat Slug: C19200 copper with Ni-Pd-Au plating
5. Lead frame: C19400 copper with SNi-Pd-Au plating.
6. Mold compound: MP-8000AN or EME6600HR epoxy
7. Package weight: .086 oz. [2.44 g]
8. Suggested surface mount layout for reference only.

TOLERANCES - UNLESS OTHERWISE SPECIFIED
 .XX = ±.01 [.254]
 .XXX = ±.005 [.127]
 ANG. = ±5°



TITLE: JEDEC MO-166, 20-pin PSOP
 SUBJECT: PACKAGE OUTLINE
 ENGINEER: D-M DRAWN BY: R.MOR DCA: 13227 SH. OF 1 FILENAME: DK REV: G DATE: 29MAY13

MODEL: **DK**
 FILENAME: DK REV: G DATE: 29MAY13

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